



Solder plus Support

M8 SOLDER PASTE



M8 SOLDER PASTE AT A GLANCE

- ▶ Halogen-free
- ▶ Low voiding on BGA and BTC components
- ▶ REACH and RoHS compliant
- ▶ For use with demanding, high density electronic assemblies
- ▶ High SIR/Electrically safe residue
- ▶ Formulated for use with T4 and finer powders
- ▶ Mitigates head-in-pillow



AIM, a leading global manufacturer of solder assembly materials for the electronics industry, introduces M8 Solder Paste, a high reliability no clean paste for use with SAC305 and Sn/Pb alloys.

M8 NO CLEAN SOLDER PASTE is designed for the most demanding high density electronic assemblies. An evolution of the highly successful NC258 platform, M8 brings no clean solder paste to the next level. Developed in combination with T4 and finer mesh lead-free alloy powders, M8 provides stable transfer efficiencies required for today's challenging applications. A novel activator system provides powerful, durable wetting action accommodating a wide range of profiling processes and techniques. M8 eliminates HiP defects on BGA and reduced voiding on QFN/BTC components while producing bright shiny solder joints. M8 leaves minimal, high purity residue, engineered to be safely left in place. Developed with the input of coating and cleaning industry partners, residues can be directly coated or easily removed.

